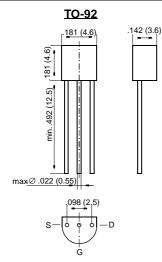
2N7000

DMOS Transistors (N-Channel)



Dimensions in inches and (millimeters)

FEATURES

- High input impedance
- Low gate threshold voltage
- Low drain-source ON resistance
- High-speed switching
- No minority carrier storage time
- CMOS logic compatible input
- No thermal runaway
- No secondary breakdown



MECHANICAL DATA

Case: TO-92 Plastic Package **Weight:** approx. 0.18 g

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	60	V	
Drain-Gate Voltage	V _{DGS}	60	V	
Gate-Source Voltage (pulsed)	V _{GS}	± 20	V	
Drain Current (continuous)	ID	300	mA	
Power Dissipation at $T_{amb} = 25 \text{ °C}$	P _{tot}	830 ¹⁾	mW	
Junction Temperature	Tj	150	°C	
Storage Temperature Range	T _S	-65 to +150	°C	
¹⁾ Valid provided that leads are kept at ambient temp	perature at a distance of 2 mm	from case.	_	

Inverse Diode

	Symbol	Value	Unit
Max. Forward Current (continuous) at T _{amb} = 25 °C	lF	500	mA
Forward Voltage Drop (typ.) at $V_{GS} = 0$, $I_F = 0.5 \text{ A}$, $T_j = 25 \text{ °C}$	V _F	850	mV



2N7000

ELECTRICAL CHARACTERISTICS

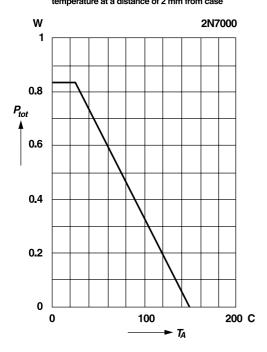
Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage at $I_D = 100 \ \mu$ A, $V_{GS} = 0 \ V$	V _(BR) DSS	60	90	-	V
Gate-Body Leakage Current, Forward at V_{GSF} = 20 V, V_{DS} = 0 V	I _{GSSF}	-	-	10	nA
Gate-Body Leakage Current, Reverse at V_{GSR} = -20 V, V_{DS} = 0 V	I _{GSSR}	-	-	-10	nA
Drain Cutoff Current at V_{DS} = 48 V, V_{GS} = 0 V	I _{DSS}	-	-	1	μΑ
Gate-Source Threshold Voltage at $V_{GS} = V_{DS}$, $I_D = 1.0$ mA	V _{GS(th)}	0.8	1.5	3	V
Drain-Source ON Resistance at V_{GS} = 10 V, I_D = 500 mA	R _{DS(ON)}	-	3.5	5.0	Ω
Capacitance at V_{DS} = 25 V, V_{GS} = 0 V, f = 1 MHz Input Capacitance Output Capacitance Feedback Capacitance	C _{iSS} C _{OSS} C _{rSS}	- - -	60 25 5		pF pF pF
Switching Times at V _{GS} = 10 V, V _{DS} = 10 V, R _D = 100 Ω Turn-On Time Turn-Off Time	t _{on} t _{off}		10 10		ns ns
Thermal Resistance Junction to Ambient Air	R _{thJA}	_	_	150 ¹⁾	K/W

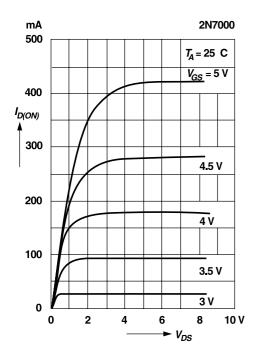
GENERAL SEMICONDUCTOR®

RATINGS AND CHARACTERISTIC CURVES 2N7000

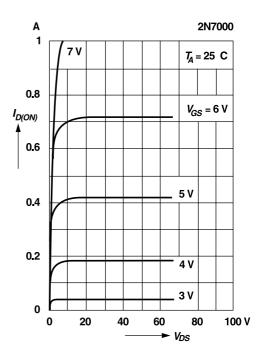
Admissible power dissipation versus temperature Valid provided that leads are kept at ambient temperature at a distance of 2 mm from case



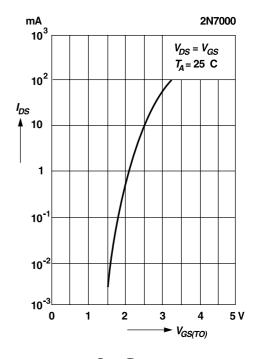
Saturation characteristics Pulse test width 80 ms; pulse duty factor 1%.



Output characteristics Pulse test width 80 ms; pulse duty factor 1%.



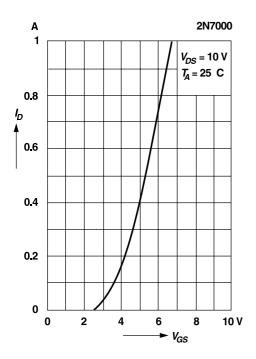
Drain-source current versus gate threshold voltage



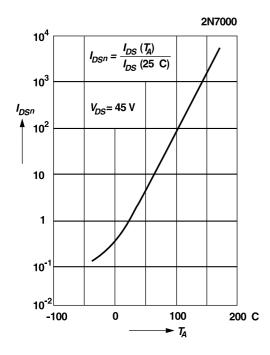
GENERAL SEMICONDUCTOR[®]

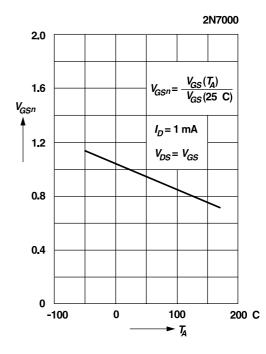
RATINGS AND CHARACTERISTIC CURVES 2N7000

Drain current versus gate-source voltage Pulse test width 80 ms; pulse duty factor 1%.



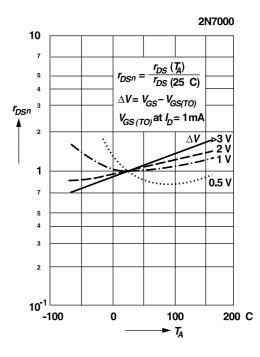
Normalized drain-source current versus temperature





Normalized gate-source voltage versus temperature

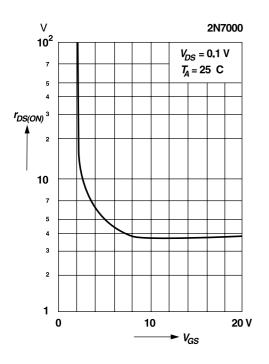
Normalized drain-source resistance versus temperature



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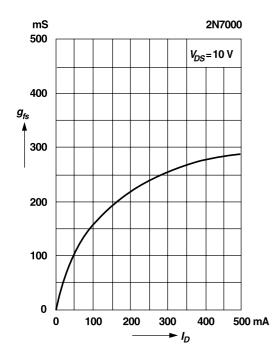
RATINGS AND CHARACTERISTIC CURVES 2N7000

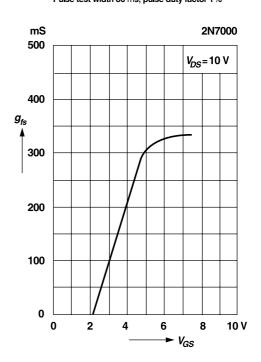
Drain-source resistance versus gate-source voltage



Transconductance versus drain current

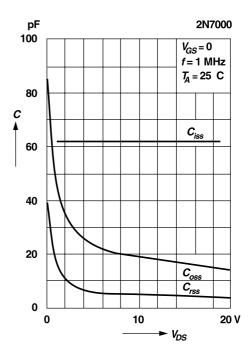
Pulse test width 80 ms; pulse duty factor 1%





Transconductance versus gate-source voltage Pulse test width 80 ms; pulse duty factor 1%

Capacitance versus drain-source voltage



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